



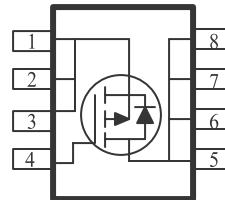
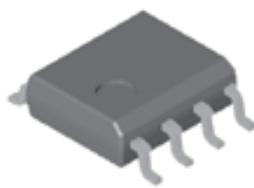
## P-Channel 60-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize High Cell Density process. Low  $r_{DS(on)}$  assures minimal power loss and conserves energy, making this device ideal for use in power management circuitry. Typical applications are PWMDC-DC converters, power management in portable and battery-powered products such as computers, printers, battery charger, telecommunication power system, and telephones power system.

- Low  $r_{DS(on)}$  Provides Higher Efficiency and Extends Battery Life
- Miniature SO-8 Surface Mount Package Saves Board Space
- High power and current handling capability
- Extended VGS range ( $\pm 25$ ) for battery pack applications

### PRODUCT SUMMARY

V <sub>DS</sub> (V)	r <sub>DS(on)</sub> m(Ω)	I <sub>D</sub> (A)
-60	17 @ V <sub>GS</sub> = -10V	-9.3
	23 @ V <sub>GS</sub> = -4.5V	-8.0



### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V <sub>DS</sub>	-60	V
Gate-Source Voltage	V <sub>GS</sub>	$\pm 20$	
Continuous Drain Current <sup>a</sup>	I <sub>D</sub>	$\pm 9.3$	A
		$\pm 8.0$	
Pulsed Drain Current <sup>b</sup>	I <sub>DM</sub>	$\pm 30$	
Continuous Source Current (Diode Conduction) <sup>a</sup>	I <sub>S</sub>	-2.5	A
Power Dissipation <sup>a</sup>	P <sub>D</sub>	3.1	W
		2.0	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Maximum	Units
Maximum Junction-to-Ambient <sup>a</sup>	R <sub>θJA</sub>	50	°C/W

#### Notes

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

**SPECIFICATIONS ( $T_A = 25^\circ\text{C}$  UNLESS OTHERWISE NOTED)**

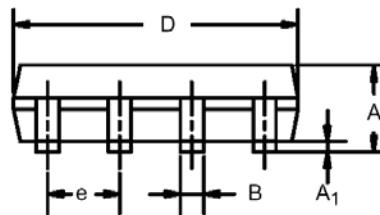
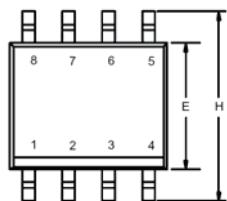
Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
<b>Static</b>						
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	-1			
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -48 \text{ V}, V_{GS} = 0 \text{ V}$			-1	$\mu\text{A}$
		$V_{DS} = -48 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$			-10	
On-State Drain Current <sup>A</sup>	$I_{D(\text{on})}$	$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	-20			A
Drain-Source On-Resistance <sup>A</sup>	$r_{DS(\text{on})}$	$V_{GS} = -10 \text{ V}, I_D = -9.3 \text{ A}$			17	$\text{m}\Omega$
		$V_{GS} = -4.5 \text{ V}, I_D = -8.0 \text{ A}$			23	
Forward Tranconductance <sup>A</sup>	$g_{fs}$	$V_{DS} = -15 \text{ V}, I_D = -9.3 \text{ A}$		8		S
Diode Forward Voltage	$V_{SD}$	$I_S = -2.5 \text{ A}, V_{GS} = 0 \text{ V}$			-1.2	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = -30 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -8.0 \text{ A}$		46		nC
Gate-Source Charge	$Q_{gs}$			18		
Gate-Drain Charge	$Q_{gd}$			41		
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = -30 \text{ V}, R_L = 30 \Omega, I_D = -1 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 6\Omega$		20		nS
Rise Time	$t_r$			20		
Turn-Off Delay Time	$t_{d(\text{off})}$			205		
Fall-Time	$t_f$			90		

## Notes

- a. Pulse test: PW <= 300us duty cycle <= 2%.
- b. Guaranteed by design, not subject to production testing.

## Package Information

SO-8: 8LEAD



Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
<b>A</b>	1.35	1.75	0.053	0.069
<b>A<sub>1</sub></b>	0.10	0.20	0.004	0.008
<b>B</b>	0.35	0.51	0.014	0.020
<b>C</b>	0.19	0.25	0.0075	0.010
<b>D</b>	4.80	5.00	0.189	0.196
<b>E</b>	3.80	4.00	0.150	0.157
<b>e</b>	1.27 BSC		0.050 BSC	
<b>H</b>	5.80	6.20	0.228	0.244
<b>h</b>	0.25	0.50	0.010	0.020
<b>L</b>	0.50	0.93	0.020	0.037
<b>q</b>	0°	8°	0°	8°

